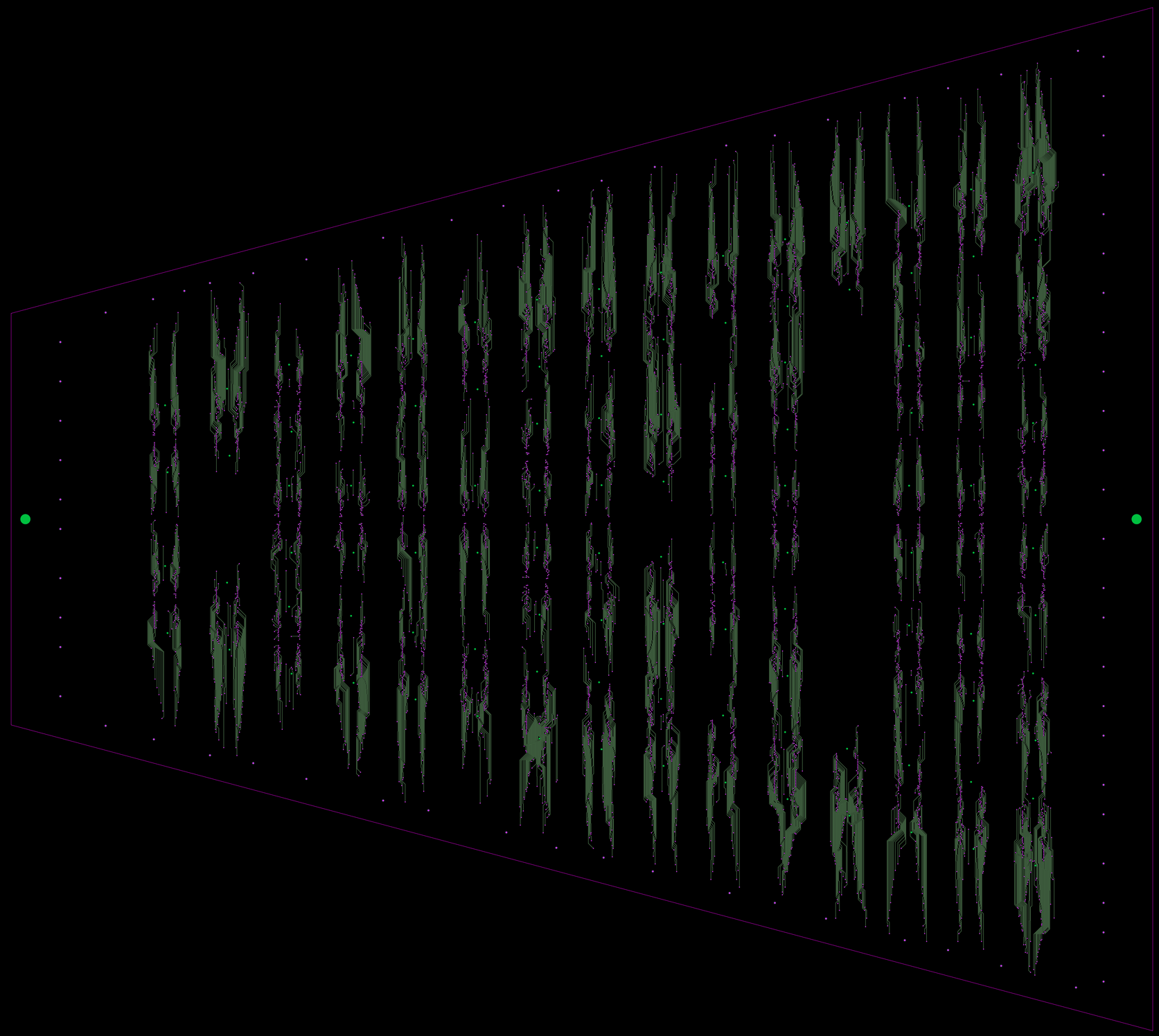
iTPC Padplane revC

Layer 1

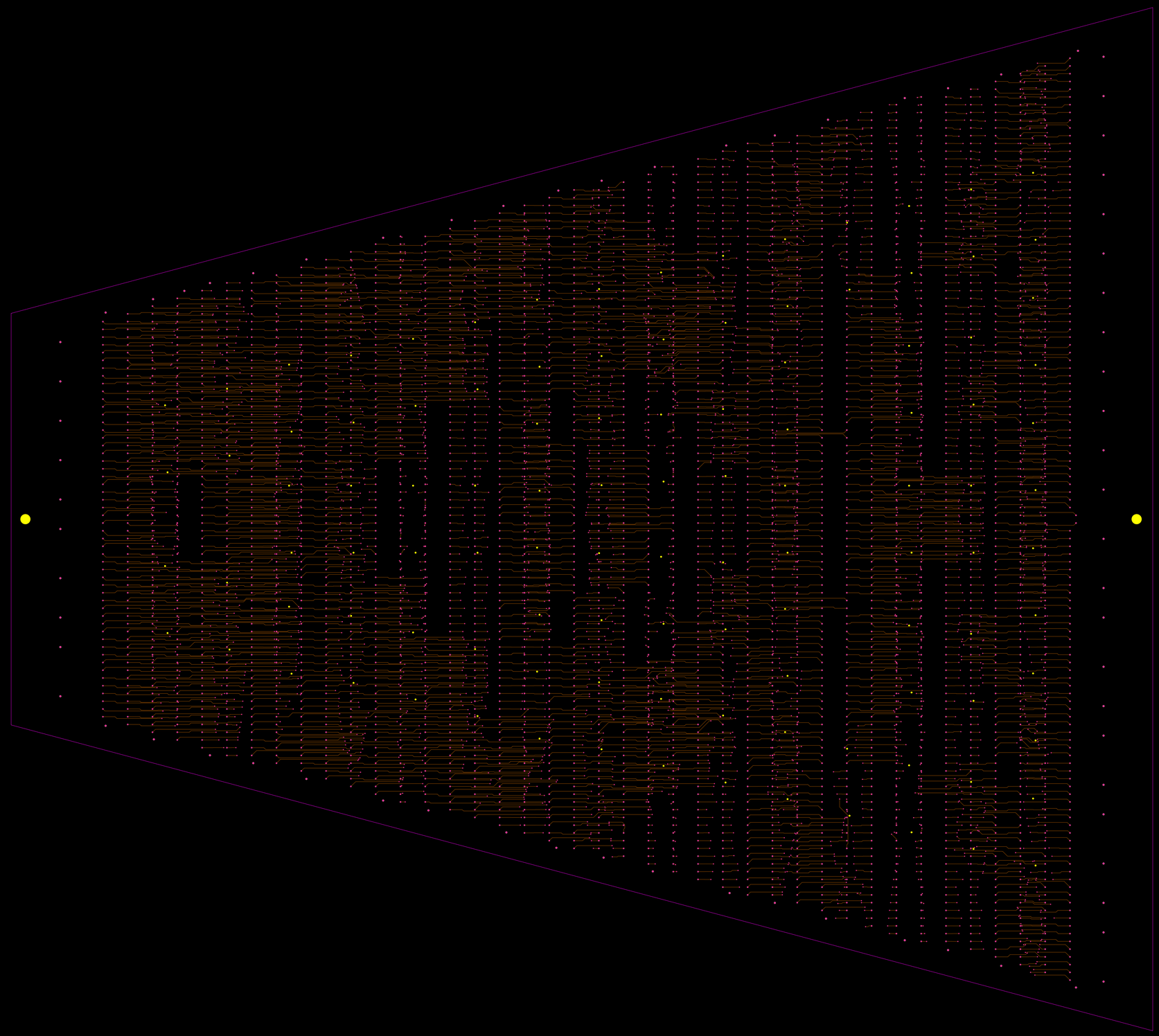
iTPC Padplane revC

Layer 2



iTPC Padplane revC

Layer 3



iTPC Padplane revC

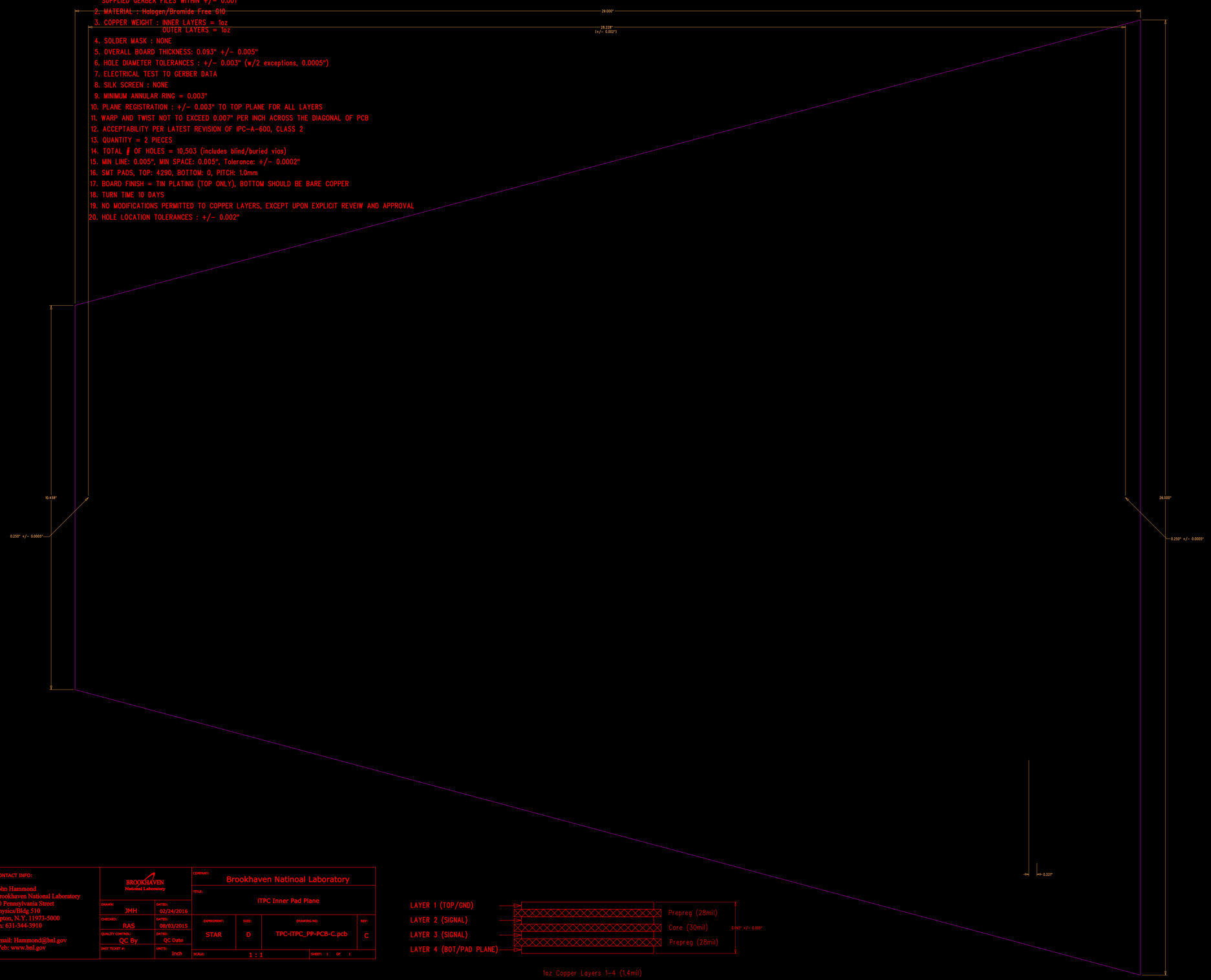
Layer 4

FABRICATION NOTES:

1. FINISHED TRACE AND LINE WIDTHS SHOULD MATCH SUPPLIED GERBER FILES WITHIN +/- 0.001"
2. MATERIAL : Halogen/Bromide Free G10
3. COPPER WEIGHT : INNER LAYERS = 1oz
   OUTER LAYERS = 1oz
4. SOLDER MASK : NONE
5. OVERALL BOARD THICKNESS: 0.093" +/- 0.005"
6. HOLE DIAMETER TOLERANCES : +/- 0.003" (w/2 exceptions, 0.0005")
7. ELECTRICAL TEST TO GERBER DATA
8. SILK SCREEN : NONE
9. MINIMUM ANNULAR RING = 0.003"
10. PLANE REGISTRATION : +/- 0.003" TO TOP PLANE FOR ALL LAYERS
11. WARP AND TWIST NOT TO EXCEED 0.007" PER INCH ACROSS THE DIAGONAL OF PCB
12. ACCEPTABILITY PER LATEST REVISION OF IPC-A-600, CLASS 2
13. QUANTITY = 2 PIECES
14. TOTAL # OF HOLES = 10,503 (includes blind/buried vias)
15. MIN LINE: 0.005", MIN SPACE: 0.005", Tolerance: +/- 0.0002"
16. SMT PADS, TOP: 4290, BOTTOM: 0, PITCH: 1.0mm
17. BOARD FINISH = TIN PLATING (TOP ONLY), BOTTOM SHOULD BE BARE COPPER
18. TURN TIME 10 DAYS
19. NO MODIFICATIONS PERMITTED TO COPPER LAYERS, EXCEPT UPON EXPLICIT REVEIW AND APPROVAL
20. HOLE LOCATION TOLERANCES : +/- 0.002"

iTPC Padplane revC

Fabrication Drawing



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BROOKHAVEN National Laboratory

DRAWN: JMH	DATED: 02/24/2016	COMPANY: Brookhaven Natinoal Laboratory	
CHECKED: RAS	DATED: 08/03/2015	TITLE: iTPC Inner Pad Plane	
QUALITY CONTROL: QC By	DATED: QC Date	EXPERIMENT: STAR / SIZE: D / DRAWING NO: TPC-iTPC_PP-PCB-C.pcb	REV: C
INST TICKET #:	UNITS: Inch	SCALE: 1 : 1	SHEET: 1 OF 1

1oz Copper Layers 1-4 (1.4mil)